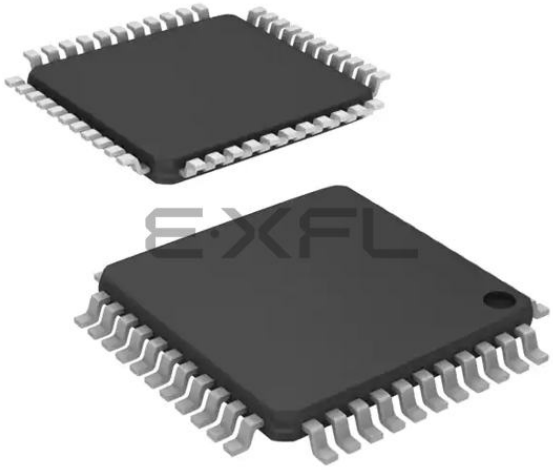
Microchip Technology - DSPIC33FJ64GP804-I/PT Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DCI, DMA, I²S, POR, PWM, WDT
Number of I/O	35
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 13x10b/12b; D/A 2x16b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj64gp804-i-pt

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REGISTER 3-2: CORCON: CORE CONTROL REGISTER

U-0	U-0	U-0	R/W-0	R/W-0	R-0	R-0	R-0
—	—	—	US	EDT(1)	DL<2:0>		
bit 15							bit 8

R/W-0	R/W-0	R/W-1	R/W-0	R/C-0	R/W-0	R/W-0	R/W-0
SATA	SATB	SATDW	ACCSAT	IPL3(2)	PSV	RND	IF
bit 7							bit 0

Legend:	C = Clear only bit		
R = Readable bit	W = Writable bit	-n = Value at POR	'1' = Bit is set
0' = Bit is cleared	'x = Bit is unknown	U = Unimplemented bit, read as '0'	

bit 15-13 **Unimplemented:** Read as '0'

bit 12 **US:** DSP Multiply Unsigned/Signed Control bit
1 = DSP engine multiplies are unsigned
0 = DSP engine multiplies are signed

bit 11 **EDT:** Early DO Loop Termination Control bit(1)
1 = Terminate executing DO loop at end of current loop iteration
0 = No effect

bit 10-8 **DL<2:0>:** DO Loop Nesting Level Status bits
111 = 7 DO loops active
•
•
•
001 = 1 DO loop active
000 = 0 DO loops active

bit 7 **SATA:** ACCA Saturation Enable bit
1 = Accumulator A saturation enabled
0 = Accumulator A saturation disabled

bit 6 **SATB:** ACCB Saturation Enable bit
1 = Accumulator B saturation enabled
0 = Accumulator B saturation disabled

bit 5 **SATDW:** Data Space Write from DSP Engine Saturation Enable bit
1 = Data space write saturation enabled
0 = Data space write saturation disabled

bit 4 **ACCSAT:** Accumulator Saturation Mode Select bit
1 = 9.31 saturation (super saturation)
0 = 1.31 saturation (normal saturation)

bit 3 **IPL3:** CPU Interrupt Priority Level Status bit 3(2)
1 = CPU interrupt priority level is greater than 7
0 = CPU interrupt priority level is 7 or less

bit 2 **PSV:** Program Space Visibility in Data Space Enable bit
1 = Program space visible in data space
0 = Program space not visible in data space

bit 1 **RND:** Rounding Mode Select bit
1 = Biased (conventional) rounding enabled
0 = Unbiased (convergent) rounding enabled

bit 0 **IF:** Integer or Fractional Multiplier Mode Select bit
1 = Integer mode enabled for DSP multiply ops
0 = Fractional mode enabled for DSP multiply ops

Note 1: This bit is always read as '0'.
2: The IPL3 bit is concatenated with the IPL<2:0> bits (SR<7:5>) to form the CPU interrupt priority level.

REGISTER 7-4: INTCON2: INTERRUPT CONTROL REGISTER 2

R/W-0	R-0	U-0	U-0	U-0	U-0	U-0	U-0
ALTIVT	DISI	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	INT2EP	INT1EP	INT0EP
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ALTIVT:** Enable Alternate Interrupt Vector Table bit
1 = Use alternate vector table
0 = Use standard (default) vector table

bit 14 **DISI:** DISI Instruction Status bit
1 = DISI instruction is active
0 = DISI instruction is not active

bit 13-3 **Unimplemented:** Read as '0'

bit 2 **INT2EP:** External Interrupt 2 Edge Detect Polarity Select bit
1 = Interrupt on negative edge
0 = Interrupt on positive edge

bit 1 **INT1EP:** External Interrupt 1 Edge Detect Polarity Select bit
1 = Interrupt on negative edge
0 = Interrupt on positive edge

bit 0 **INT0EP:** External Interrupt 0 Edge Detect Polarity Select bit
1 = Interrupt on negative edge
0 = Interrupt on positive edge

REGISTER 7-11: IEC1: INTERRUPT ENABLE CONTROL REGISTER 1 (CONTINUED)

bit 2 **CMIE:** Comparator Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 1 **MI2C1IE:** I2C1 Master Events Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 0 **SI2C1IE:** I2C1 Slave Events Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

11.0 I/O PORTS

Note 1: This data sheet summarizes the features of the dsPIC33FJ32GP302/304, dsPIC33FJ64GPX02/X04, and dsPIC33FJ128GPX02/X04 families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section "30. I/O Ports with Peripheral Pin Select"** (DS70190) of the "*dsPIC33F/PIC24H Family Reference Manual*", which is available from the Microchip website (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

All of the device pins (except VDD, VSS, MCLR and OSC1/CLKI) are shared among the peripherals and the parallel I/O ports. All I/O input ports feature Schmitt Trigger inputs for improved noise immunity.

11.1 Parallel I/O (PIO) Ports

Generally a parallel I/O port that shares a pin with a peripheral is subservient to the peripheral. The peripheral's output buffer data and control signals are provided to a pair of multiplexers. The multiplexers select whether the peripheral or the associated port has ownership of the output data and control signals of the I/O pin. The logic also prevents "loop through," in which a port's digital output can drive the input of a peripheral that shares the same pin. Figure 11-1 shows how ports are shared with other peripherals and the associated I/O pin to which they are connected.

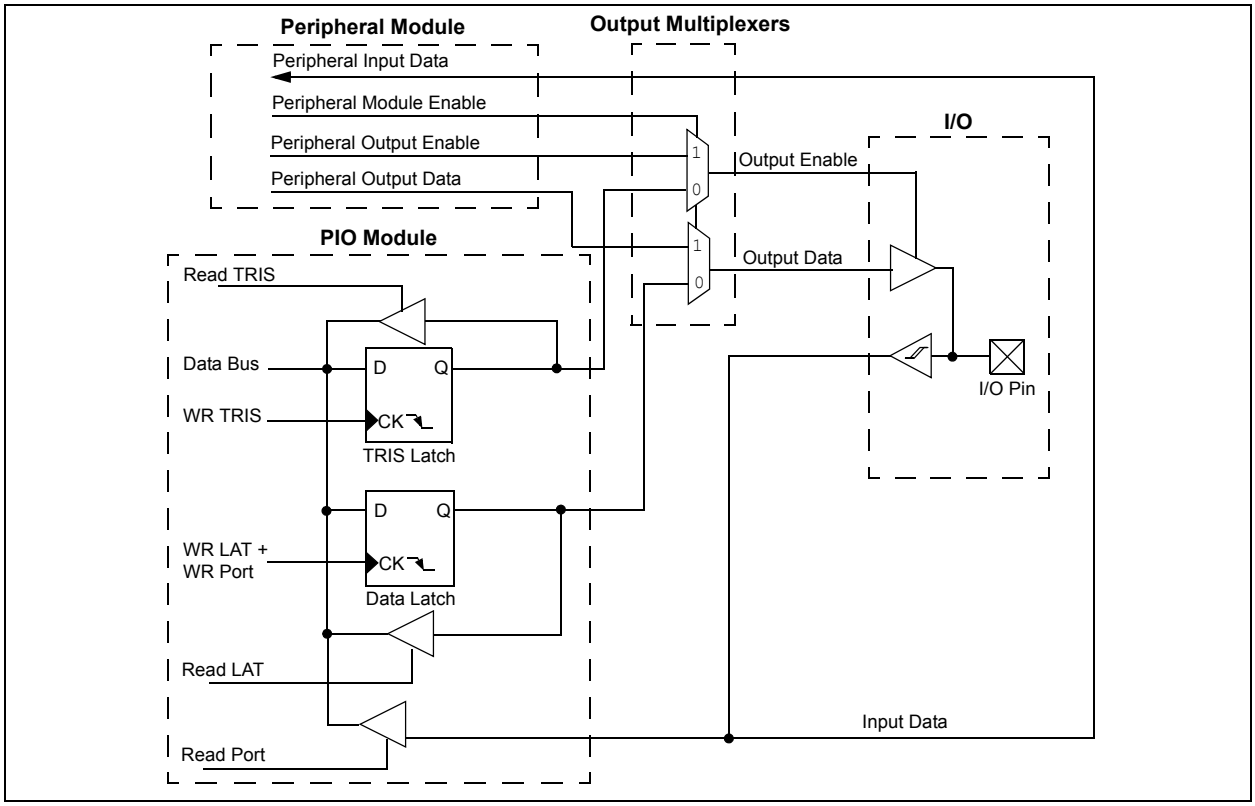
When a peripheral is enabled and the peripheral is actively driving an associated pin, the use of the pin as a general purpose output pin is disabled. The I/O pin can be read, but the output driver for the parallel port bit is disabled. If a peripheral is enabled, but the peripheral is not actively driving a pin, that pin can be driven by a port.

All port pins have three registers directly associated with their operation as digital I/O. The data direction register (TRISx) determines whether the pin is an input or an output. If the data direction bit is a '1', then the pin is an input. All port pins are defined as inputs after a Reset. Reads from the latch (LATx) read the latch. Writes to the latch write the latch. Reads from the port (PORTx) read the port pins, while writes to the port pins write the latch.

Any bit and its associated data and control registers that are not valid for a particular device is disabled. This means the corresponding LATx and TRISx registers and the port pin are read as zeros.

When a pin is shared with another peripheral or function that is defined as an input only, it is nevertheless regarded as a dedicated port because there is no other competing source of outputs.

FIGURE 11-1: BLOCK DIAGRAM OF A TYPICAL SHARED PORT STRUCTURE



REGISTER 11-13: RPINR23: PERIPHERAL PIN SELECT INPUT REGISTER 23

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	—	SS2R<4:0>				
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-5 **Unimplemented:** Read as '0'

bit 4-0 **SS2R<4:0>:** Assign SPI2 Slave Select Input ($\overline{SS2}$) to the corresponding RPn pin

11111 = Input tied to Vss
11001 = Input tied to RP25
•
•
•
00001 = Input tied to RP1
00000 = Input tied to RP0

14.0 INPUT CAPTURE

Note 1: This data sheet summarizes the features of the dsPIC33FJ32GP302/304, dsPIC33FJ64GPX02/X04, and dsPIC33FJ128GPX02/X04 families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 12. "Input Capture"** (DS70198) of the "*dsPIC33F/PIC24H Family Reference Manual*", which is available from the Microchip website (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The input capture module is useful in applications requiring frequency (period) and pulse measurement. The dsPIC33FJ32GP302/304, dsPIC33FJ64GPX02/X04, and dsPIC33FJ128GPX02/X04 devices support up to four input capture channels.

The input capture module captures the 16-bit value of the selected Time Base register when an event occurs at the ICx pin. The events that cause a capture event are listed below in three categories:

1. Simple Capture Event modes:
   - Capture timer value on every falling edge of input at ICx pin
   - Capture timer value on every rising edge of input at ICx pin
2. Capture timer value on every edge (rising and falling)
3. Prescaler Capture Event modes:
   - Capture timer value on every 4th rising edge of input at ICx pin
   - Capture timer value on every 16th rising edge of input at ICx pin

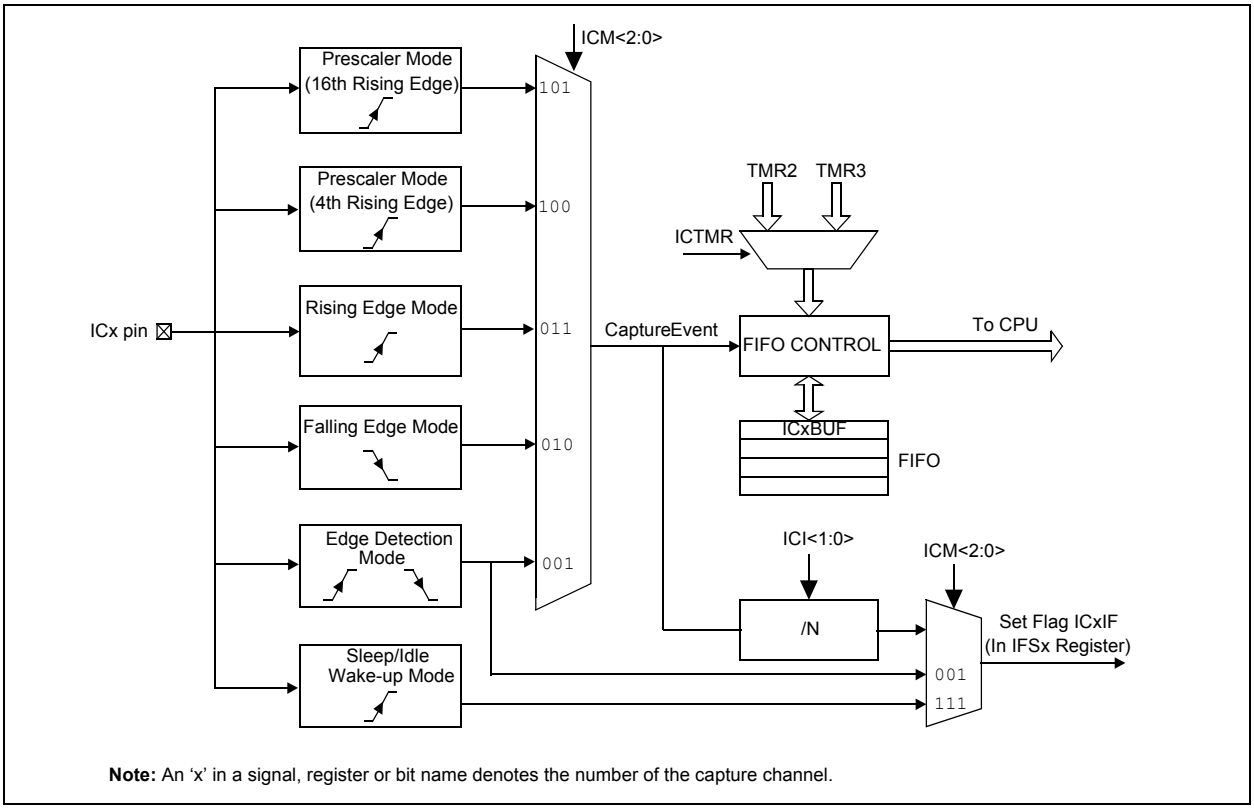
Each input capture channel can select one of two 16-bit timers (Timer2 or Timer3) for the time base. The selected timer can use either an internal or external clock.

Other operational features include:

- Device wake-up from capture pin during CPU Sleep and Idle modes
- Interrupt on input capture event
- 4-word FIFO buffer for capture values
  - Interrupt optionally generated after 1, 2, 3 or 4 buffer locations are filled
- Use of input capture to provide additional sources of external interrupts

Note: Only IC1 and IC2 can trigger a DMA data transfer. If DMA data transfers are required, the FIFO buffer size must be set to '1' (ICI<1:0> = 00)

FIGURE 14-1: INPUT CAPTURE BLOCK DIAGRAM



Note: An 'x' in a signal, register or bit name denotes the number of the capture channel.

REGISTER 19-20: CiRXMnSID: ECAN™ ACCEPTANCE FILTER MASK STANDARD IDENTIFIER REGISTER n (n = 0-2)

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
SID10	SID9	SID8	SID7	SID6	SID5	SID4	SID3
bit 15							bit 8

R/W-x	R/W-x	R/W-x	U-0	R/W-x	U-0	R/W-x	R/W-x
SID2	SID1	SID0	—	MIDE	—	EID17	EID16
bit 7							bit 0

Legend:	C = Writable bit, but only '0' can be written to clear the bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-5 **SID<10:0>:** Standard Identifier bits
1 = Include bit SIDx in filter comparison
0 = Bit SIDx is don't care in filter comparison

bit 4 **Unimplemented:** Read as '0'

bit 3 **MIDE:** Identifier Receive Mode bit
1 = Match only message types (standard or extended address) that correspond to EXIDE bit in filter
0 = Match either standard or extended address message if filters match
(i.e., if (Filter SID) = (Message SID) or if (Filter SID/EID) = (Message SID/EID))

bit 2 **Unimplemented:** Read as '0'

bit 1-0 **EID<17:16>:** Extended Identifier bits
1 = Include bit EIDx in filter comparison
0 = Bit EIDx is don't care in filter comparison

REGISTER 19-21: CiRXMnEID: ECAN™ ACCEPTANCE FILTER MASK EXTENDED IDENTIFIER REGISTER n (n = 0-2)

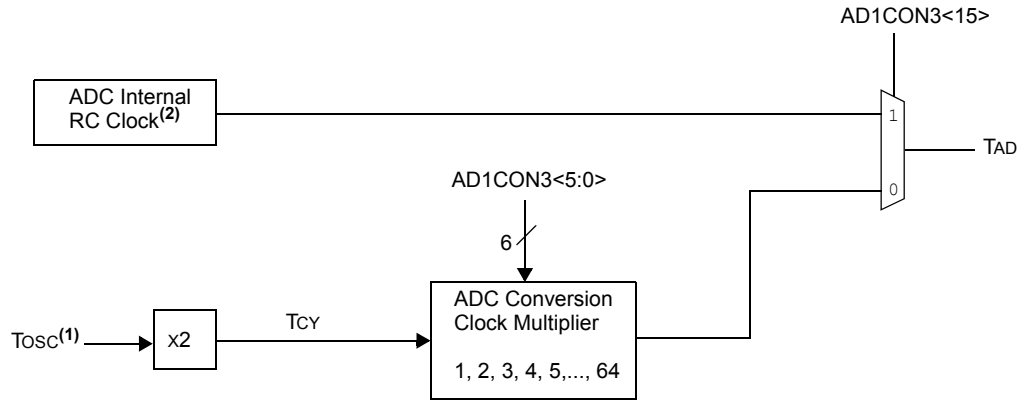
R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
EID15	EID14	EID13	EID12	EID11	EID10	EID9	EID8
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
EID7	EID6	EID5	EID4	EID3	EID2	EID1	EID0
bit 7							bit 0

Legend:	C = Writable bit, but only '0' can be written to clear the bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **EID<15:0>:** Extended Identifier bits
1 = Include bit EIDx in filter comparison
0 = Bit EIDx is don't care in filter comparison

FIGURE 21-3: ADC CONVERSION CLOCK PERIOD BLOCK DIAGRAM



Note 1: Refer to Figure 9-2 for the derivation of Fosc when the PLL is enabled. If the PLL is not used, Fosc is equal to the clock source frequency. Tosc = 1/Fosc.

2: See the ADC electrical characteristics for the exact RC clock value.

REGISTER 26-5: PMSTAT: PARALLEL PORT STATUS REGISTER

R-0	R/W-0, HS	U-0	U-0	R-0	R-0	R-0	R-0
IBF	IBOV	—	—	IB3F	IB2F	IB1F	IB0F
bit 15							bit 8

R-1	R/W-0, HS	U-0	U-0	R-1	R-1	R-1	R-1
OBE	OBUF	—	—	OB3E	OB2E	OB1E	OB0E
bit 7							bit 0

Legend:	HS = Hardware Set bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **IBF:** Input Buffer Full Status bit
1 = All writable input buffer registers are full
0 = Some or all of the writable input buffer registers are empty

bit 14 **IBOV:** Input Buffer Overflow Status bit
1 = A write attempt to a full input byte register occurred (must be cleared in software)
0 = No overflow occurred

bit 13-12 **Unimplemented:** Read as '0'

bit 11-8 **IB3F:IB0F:** Input Buffer x Status Full bits
1 = Input buffer contains data that has not been read (reading buffer will clear this bit)
0 = Input buffer does not contain any unread data

bit 7 **OBE:** Output Buffer Empty Status bit
1 = All readable output buffer registers are empty
0 = Some or all of the readable output buffer registers are full

bit 6 **OBUF:** Output Buffer Underflow Status bits
1 = A read occurred from an empty output byte register (must be cleared in software)
0 = No underflow occurred

bit 5-4 **Unimplemented:** Read as '0'

bit 3-0 **OB3E:OB0E:** Output Buffer x Status Empty bit
1 = Output buffer is empty (writing data to the buffer will clear this bit)
0 = Output buffer contains data that has not been transmitted

28.0 INSTRUCTION SET SUMMARY

Note: This data sheet summarizes the features of the dsPIC33FJ32GP302/304, dsPIC33FJ64GPX02/X04, and dsPIC33FJ128GPX02/X04 families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the *"dsPIC33F/PIC24H Family Reference Manual"*. Please see the Microchip web site (www.microchip.com) for the latest reference manual sections.

The dsPIC33F instruction set is identical to that of the dsPIC30F.

Most instructions are a single program memory word (24 bits). Only three instructions require two program memory locations.

Each single-word instruction is a 24-bit word, divided into an 8-bit opcode, which specifies the instruction type and one or more operands, which further specify the operation of the instruction.

The instruction set is highly orthogonal and is grouped into five basic categories:

- Word or byte-oriented operations
- Bit-oriented operations
- Literal operations
- DSP operations
- Control operations

Table 28-1 shows the general symbols used in describing the instructions.

The dsPIC33F instruction set summary in Table 28-2 lists all the instructions, along with the status flags affected by each instruction.

Most word or byte-oriented W register instructions (including barrel shift instructions) have three operands:

- The first source operand, which is typically a register 'Wb' without any address modifier
- The second source operand, which is typically a register 'Ws' with or without an address modifier
- The destination of the result, which is typically a register 'Wd' with or without an address modifier

However, word or byte-oriented file register instructions have two operands:

- The file register specified by the value 'f'
- The destination, which could be either the file register 'f' or the W0 register, which is denoted as 'WREG'

Most bit-oriented instructions (including simple rotate/shift instructions) have two operands:

- The W register (with or without an address modifier) or file register (specified by the value of 'Ws' or 'f')
- The bit in the W register or file register (specified by a literal value or indirectly by the contents of register 'Wb')

The literal instructions that involve data movement can use some of the following operands:

- A literal value to be loaded into a W register or file register (specified by 'k')
- The W register or file register where the literal value is to be loaded (specified by 'Wb' or 'f')

However, literal instructions that involve arithmetic or logical operations use some of the following operands:

- The first source operand, which is a register 'Wb' without any address modifier
- The second source operand, which is a literal value
- The destination of the result (only if not the same as the first source operand), which is typically a register 'Wd' with or without an address modifier

The MAC class of DSP instructions can use some of the following operands:

- The accumulator (A or B) to be used (required operand)
- The W registers to be used as the two operands
- The X and Y address space prefetch operations
- The X and Y address space prefetch destinations
- The accumulator write back destination

The other DSP instructions do not involve any multiplication and can include:

- The accumulator to be used (required)
- The source or destination operand (designated as Wso or Wdo, respectively) with or without an address modifier
- The amount of shift specified by a W register 'Wn' or a literal value

The control instructions can use some of the following operands:

- A program memory address
- The mode of the table read and table write instructions

TABLE 30-17: PLL CLOCK TIMING SPECIFICATIONS (V_{DD} = 3.0V TO 3.6V)

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
OS50	FPLLI	PLL Voltage Controlled Oscillator (VCO) Input Frequency Range	0.8	—	8	MHz	ECPLL, HSPLL, XTPLL modes
OS51	FSYS	On-Chip VCO System Frequency	100	—	200	MHz	—
OS52	TLOCK	PLL Start-up Time (Lock Time)	0.9	1.5	3.1	mS	—
OS53	DCLK	CLKO Stability (Jitter)(2)	-3	0.5	3	%	Measured over 100 ms period

Note 1: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: These parameters are characterized by similarity, but are not tested in manufacturing. This specification is based on clock cycle by clock cycle measurements. To calculate the effective jitter for individual time bases or communication clocks use this formula:

$$Peripheral\ Clock\ Jitter = \frac{DCLK}{\sqrt{\left(\frac{FOSC}{Peripheral\ Bit\ Rate\ Clock}\right)}}$$

For example: Fosc = 32 MHz, DCLK = 3%, SPI bit rate clock, (i.e., SCK) is 2 MHz.

$$SPI\ SCK\ Jitter = \left[\frac{DCLK}{\sqrt{\left(\frac{32\ MHz}{2\ MHz}\right)}}\right] = \left[\frac{3\%}{\sqrt{16}}\right] = \left[\frac{3\%}{4}\right] = 0.75\%$$

TABLE 30-18: AC CHARACTERISTICS: INTERNAL RC ACCURACY

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended					
Param No.	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**	
	Internal FRC Accuracy @ 7.3728 MHz(1)						
F20a	FRC	-2	—	+2	%	-40°C ≤ TA ≤ +85°C	VDD = 3.0-3.6V
F20b	FRC	-5	—	+5	%	-40°C ≤ TA ≤ +125°C	VDD = 3.0-3.6V

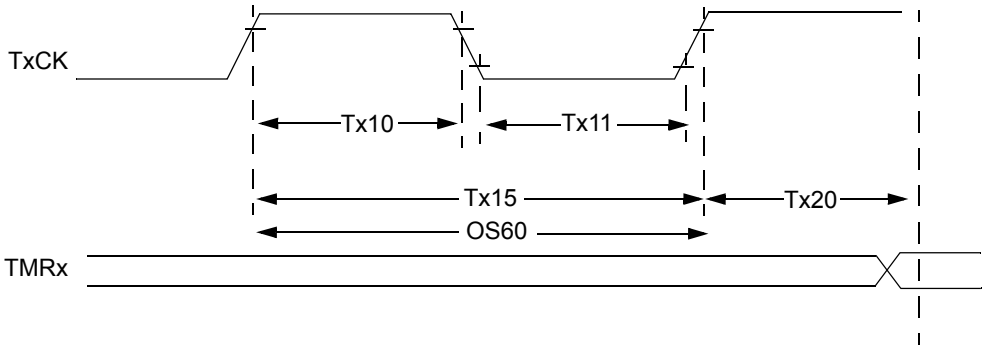
Note 1: Frequency calibrated at 25°C and 3.3V. TUN bits can be used to compensate for temperature drift.

TABLE 30-19: INTERNAL RC ACCURACY

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended					
Param No.	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**	
	LPRC @ 32.768 kHz(1)						
F21a	LPRC	-20	±6	+20	%	-40°C ≤ TA ≤ +85°C	VDD = 3.0-3.6V
F21b	LPRC	-30	—	+30	%	-40°C ≤ TA ≤ +125°C	VDD = 3.0-3.6V

Note 1: Change of LPRC frequency as VDD changes.

FIGURE 30-5: TIMER1, 2, 3 AND 4 EXTERNAL CLOCK TIMING CHARACTERISTICS



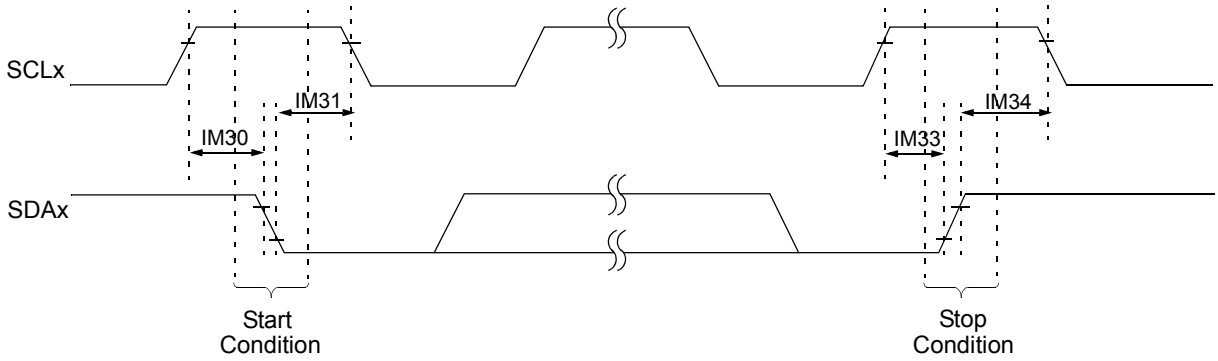
Note: Refer to Figure 30-1 for load conditions.

TABLE 30-22: TIMER1 EXTERNAL CLOCK TIMING REQUIREMENTS(1)

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**		**Min**	**Typ**	**Max**	**Units**	**Conditions**
TA10	TTxH	TxCK High Time	Synchronous, no prescaler	TCY + 20	—	—	ns	Must also meet parameter TA15. N = prescale value (1, 8, 64, 256)
			Synchronous, with prescaler	(TCY + 20)/N	—	—	ns	
			Asynchronous	20	—	—	ns	
TA11	TTxL	TxCK Low Time	Synchronous, no prescaler	(TCY + 20)	—	—	ns	Must also meet parameter TA15. N = prescale value (1, 8, 64, 256)
			Synchronous, with prescaler	(TCY + 20)/N	—	—	ns	
			Asynchronous	20	—	—	ns	
TA15	TTxP	TxCK Input Period	Synchronous, no prescaler	2 TCY + 40	—	—	ns	—
			Synchronous, with prescaler	Greater of: 40 ns or (2 TCY + 40)/ N	—	—	—	N = prescale value (1, 8, 64, 256)
			Asynchronous	40	—	—	ns	—
OS60	Ft1	SOSCI/T1CK Oscillator Input frequency Range (oscillator enabled by setting bit TCS (T1CON<1>))		DC	—	50	kHz	—
TA20	TCKEXTMRL	Delay from External TxCK Clock Edge to Timer Increment		0.75 TCY + 40	—	1.75 TCY + 40	—	—

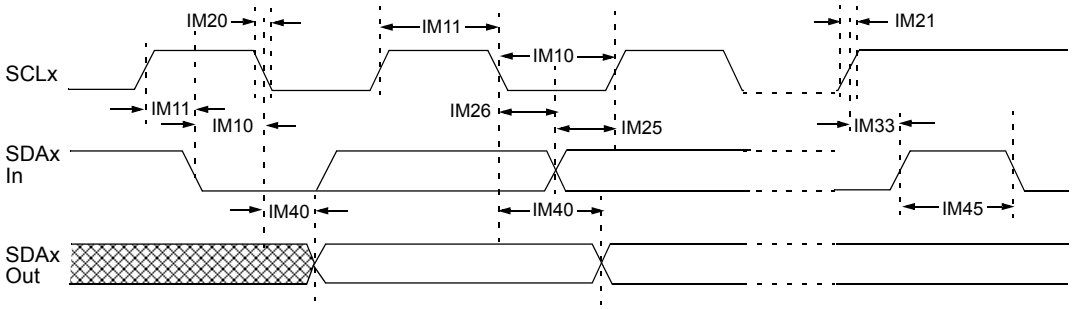
Note 1: Timer1 is a Type A.

FIGURE 30-17: I2Cx BUS START/STOP BITS TIMING CHARACTERISTICS (MASTER MODE)



Note: Refer to Figure 30-1 for load conditions.

FIGURE 30-18: I2Cx BUS DATA TIMING CHARACTERISTICS (MASTER MODE)



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-38: DCI MODULE (MULTI-CHANNEL, I^2S MODES) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
CS10	TCSCKL	CSCK Input Low Time (CSCK pin is an input)	TCY/2 + 20	—	—	ns	—
		CSCK Output Low Time(3) (CSCK pin is an output)	30	—	—	ns	—
CS11	TCSCKH	CSCK Input High Time (CSCK pin is an input)	TCY/2 + 20	—	—	ns	—
		CSCK Output High Time(3) (CSCK pin is an output)	30	—	—	ns	—
CS20	TCSCKF	CSCK Output Fall Time(4) (CSCK pin is an output)	—	10	25	ns	—
CS21	TCSCKR	CSCK Output Rise Time(4) (CSCK pin is an output)	—	10	25	ns	—
CS30	TCSDOF	CSDO Data Output Fall Time(4)	—	10	25	ns	—
CS31	TCSDOR	CSDO Data Output Rise Time(4)	—	10	25	ns	—
CS35	TDV	Clock Edge to CSDO Data Valid	—	—	10	ns	—
CS36	TDIV	Clock Edge to CSDO Tri-Stated	10	—	20	ns	—
CS40	TCSDI	Setup Time of CSDI Data Input to CSCK Edge (CSCK pin is input or output)	20	—	—	ns	—
CS41	THCSDI	Hold Time of CSDI Data Input to CSCK Edge (CSCK pin is input or output)	20	—	—	ns	—
CS50	TCOFSF	COFS Fall Time (COFS pin is output)	—	10	25	ns	See **Note 1**
CS51	TCOFSR	COFS Rise Time (COFS pin is output)	—	10	25	ns	See **Note 1**
CS55	TSCOFS	Setup Time of COFS Data Input to CSCK Edge (COFS pin is input)	20	—	—	ns	—
CS56	THCOFS	Hold Time of COFS Data Input to CSCK Edge (COFS pin is input)	20	—	—	ns	—

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The minimum clock period for CSCK is 100 ns. Therefore, the clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all DCI pins.

31.0 HIGH TEMPERATURE ELECTRICAL CHARACTERISTICS

This section provides an overview of dsPIC33FJ32GP302/304, dsPIC33FJ64GPX02/X04, and dsPIC33FJ128GPX02/X04 electrical characteristics for devices operating in an ambient temperature range of -40°C to +150°C.

The specifications between -40°C to +150°C are identical to those shown in **Section 30.0 "Electrical Characteristics"** for operation between -40°C to +125°C, with the exception of the parameters listed in this section.

Parameters in this section begin with an H, which denotes High temperature. For example, parameter DC10 in **Section 30.0 "Electrical Characteristics"** is the Industrial and Extended temperature equivalent of HDC10.

Absolute maximum ratings for the dsPIC33FJ32GP302/304, dsPIC33FJ64GPX02/X04, and dsPIC33FJ128GPX02/X04 high temperature devices are listed below. Exposure to these maximum rating conditions for extended periods can affect device reliability. Functional operation of the device at these or any other conditions above the parameters indicated in the operation listings of this specification is not implied.

Absolute Maximum Ratings(1)

Ambient temperature under bias(4) ..... -40°C to +150°C
Storage temperature ..... -65°C to +160°C
Voltage on V_{DD} with respect to V_{SS} ..... -0.3V to +4.0V
Voltage on any pin that is not 5V tolerant with respect to V_{SS}(5) ..... -0.3V to (V_{DD} + 0.3V)
Voltage on any 5V tolerant pin with respect to V_{SS} when V_{DD} < 3.0V(5) ..... -0.3V to (V_{DD} + 0.3V)
Voltage on any 5V tolerant pin with respect to V_{SS} when $V_{DD} \geq$ 3.0V(5) ..... -0.3V to 5.6V
Maximum current out of V_{SS} pin ..... 60 mA
Maximum current into V_{DD} pin(2) ..... 60 mA
Maximum junction temperature ..... +155°C
Maximum current sourced/sunk by any 2x I/O pin(3) ..... 2 mA
Maximum current sourced/sunk by any 4x I/O pin(3) ..... 4 mA
Maximum current sourced/sunk by any 8x I/O pin(3) ..... 8 mA
Maximum current sunk by all ports combined ..... 70 mA
Maximum current sourced by all ports combined(2) ..... 70 mA

Note 1: Stresses above those listed under "Absolute Maximum Ratings" can cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods can affect device reliability.

2: Maximum allowable current is a function of device maximum power dissipation (see Table 31-2).

3: Unlike devices at 125°C and below, the specifications in this section also apply to the CLKOUT, V_{REF+}, V_{REF-}, SCLx, SDAx, PGCx, and PGDx pins.

4: AEC-Q100 reliability testing for devices intended to operate at 150°C is 1,000 hours. Any design in which the total operating time from 125°C to 150°C will be greater than 1,000 hours is not warranted without prior written approval from Microchip Technology Inc.

5: Refer to the **"Pin Diagrams"** section for 5V tolerant pins.

31.2 AC Characteristics and Timing Parameters

The information contained in this section defines dsPIC33FJ32GP302/304, dsPIC33FJ64GPX02/X04, and dsPIC33FJ128GPX02/X04 AC characteristics and timing parameters for high temperature devices. However, all AC timing specifications in this section are the same as those in **Section 30.2 "AC Characteristics and Timing Parameters"**, with the exception of the parameters listed in this section.

Parameters in this section begin with an H, which denotes High temperature. For example, parameter OS53 in **Section 30.2 "AC Characteristics and Timing Parameters"** is the Industrial and Extended temperature equivalent of HOS53.

TABLE 31-8: TEMPERATURE AND VOLTAGE SPECIFICATIONS – AC

AC CHARACTERISTICS	**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤TA ≤+150°C for High Temperature Operating voltage VDD range as described in Table 31-1.

FIGURE 31-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS

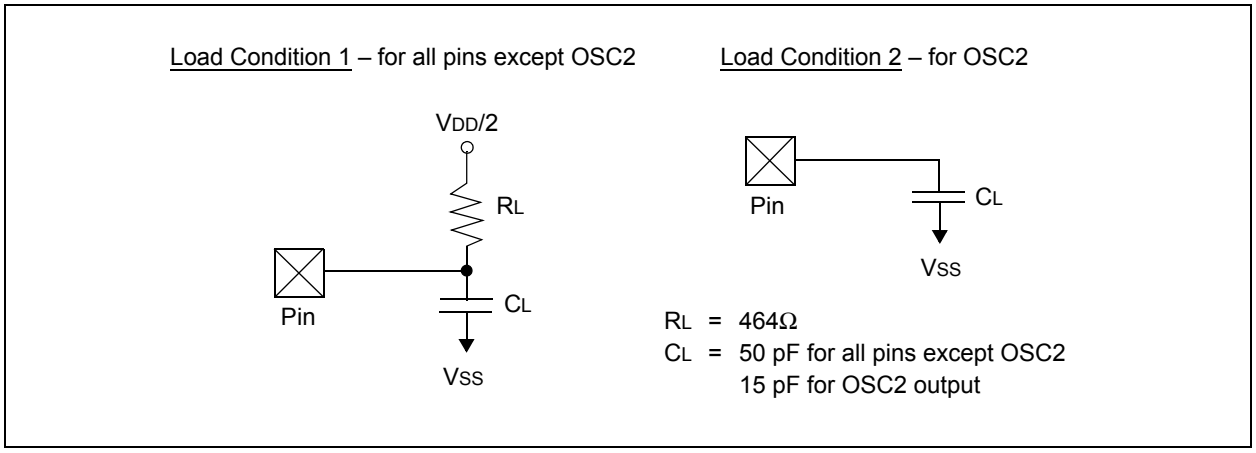


TABLE 31-9: PLL CLOCK TIMING SPECIFICATIONS

AC CHARACTERISTICS		**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤TA ≤+150°C for High Temperature					
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
HOS53	DCLK	CLKO Stability (Jitter)(1)	-5	0.5	5	%	Measured over 100 ms period

Note 1: These parameters are characterized, but are not tested in manufacturing.

TABLE 31-14: ADC MODULE SPECIFICATIONS

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+150°C for High Temperature					
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
Reference Inputs							
HAD08	IREF	Current Drain	— —	250 —	600 50	µA µA	ADC operating, See **Note 1** ADC off, See **Note 1**

Note 1: These parameters are not characterized or tested in manufacturing.

2: These parameters are characterized, but are not tested in manufacturing.

TABLE 31-15: ADC MODULE SPECIFICATIONS (12-BIT MODE)

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+150°C for High Temperature					
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
ADC Accuracy (12-bit Mode) – Measurements with External VREF+/VREF-(1)							
HAD20a	Nr	Resolution(3)	12 data bits			bits	—
HAD21a	INL	Integral Nonlinearity	-2	—	+2	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V
HAD22a	DNL	Differential Nonlinearity	> -1	—	< 1	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V
HAD23a	GERR	Gain Error	-2	—	10	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V
HAD24a	EOFF	Offset Error	-3	—	5	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V
ADC Accuracy (12-bit Mode) – Measurements with Internal VREF+/VREF-(1)							
HAD20a	Nr	Resolution(3)	12 data bits			bits	—
HAD21a	INL	Integral Nonlinearity	-2	—	+2	LSb	VINL = AVSS = 0V, AVDD = 3.6V
HAD22a	DNL	Differential Nonlinearity	> -1	—	< 1	LSb	VINL = AVSS = 0V, AVDD = 3.6V
HAD23a	GERR	Gain Error	2	—	20	LSb	VINL = AVSS = 0V, AVDD = 3.6V
HAD24a	EOFF	Offset Error	2	—	10	LSb	VINL = AVSS = 0V, AVDD = 3.6V
Dynamic Performance (12-bit Mode)(2)							
HAD33a	FNYQ	Input Signal Bandwidth	—	—	200	kHz	—

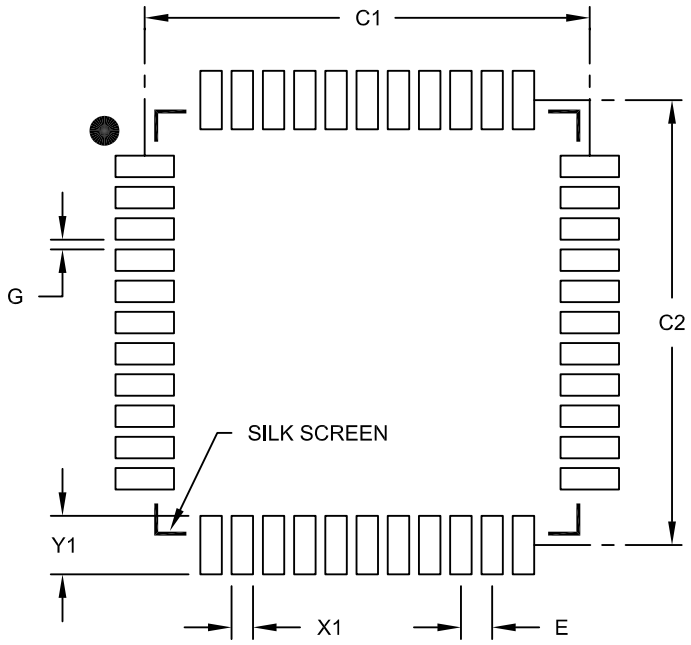
Note 1: These parameters are characterized, but are tested at 20 ksps only.

2: These parameters are characterized by similarity, but are not tested in manufacturing.

3: Injection currents > | 0 | can affect the ADC results by approximately 4-6 counts.

44-Lead Plastic Thin Quad Flatpack (PT) 10X10X1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.80 BSC	
Contact Pad Spacing	C1		11.40	
Contact Pad Spacing	C2		11.40	
Contact Pad Width (X44)	X1			0.55
Contact Pad Length (X44)	Y1			1.50
Distance Between Pads	G	0.25		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2076B

Revision C (May 2009)

This revision includes minor typographical and formatting changes throughout the data sheet text.

Global changes include:

- Changed all instances of OSCI to OSC1 and OSCO to OSC2
- Changed all instances of VDDCORE and VDDCORE/VCAP to VCAP/VDDCORE

The other changes are referenced by their respective section in the following table.

TABLE A-2: MAJOR SECTION UPDATES

Section Name	Update Description
High-Performance, 16-bit Digital Signal Controllers	Updated all pin diagrams to denote the pin voltage tolerance (see **"Pin Diagrams"**). Added Note 2 to the 28-Pin QFN-S and 44-Pin QFN pin diagrams, which references pin connections to VSS.
Section 1.0 "Device Overview"	Updated AVDD in the PINOUT I/O Descriptions (see Table 1-1). Added Peripheral Pin Select (PPS) capability column to Pinout I/O Descriptions (see Table 1-1).
Section 2.0 "Guidelines for Getting Started with 16-bit Digital Signal Controllers"	Added new section to the data sheet that provides guidelines on getting started with 16-bit Digital Signal Controllers.
Section 3.0 "CPU"	Updated CPU Core Block Diagram with a connection from the DSP Engine to the Y Data Bus (see Figure 3-1). Vertically extended the X and Y Data Bus lines in the DSP Engine Block Diagram (see Figure 3-3).
Section 4.0 "Memory Organization"	Updated Reset value for CORCON in the CPU Core Register Map (see Table 4-1). Updated the Reset values for IPC14 and IPC15 and removed the FLTA1IE bit (IEC3) from the Interrupt Controller Register Map (see Table 4-4). Updated bit locations for RPINR25 in the Peripheral Pin Select Input Register Map (see Table 4-21). Updated the Reset value for CLKDIV in the System Control Register Map (see Table 4-33).
Section 5.0 "Flash Program Memory"	Updated **Section 5.3 "Programming Operations"** with programming time formula.
Section 9.0 "Oscillator Configuration"	Updated the Oscillator System Diagram and added Note 2 (see Figure 9-1). Added Note 1 and Note 2 to the OSCON register (see Register 9-1). Updated default bit values for DOZE<2:0> and FRCDIV<2:0> in the Clock Divisor (CLKDIV) Register (see Register 9-2). Added a paragraph regarding FRC accuracy at the end of **Section 9.1.1 "System Clock Sources"**. Added Note 3 to **Section 9.2.2 "Oscillator Switching Sequence"**. Added Note 1 to the FRC Oscillator Tuning (OSCTUN) Register (see Register 9-4).